



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 500 mΩ MAX.

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|------------------------------------|--|---|--|-----------------------------------|--|
| NAME 48 PIN GRID ARRAY PACKAGE | | TOLERANCE UNLESS OTHERWISE SPECIFIED | | DRAWN CHECKED APPROVED DATE | |
| SCALE | | ± .005 | | K.I S.T./A K.M JUL.24.'92 | |
| MATERIAL AS INDICATED | | THIRD ANGLE PROJECTION | | DRAWING NO. SHEET | |
| KYOCERA CORPORATION KYOTO JAPAN | | KYOCERA | | KD-P92657 | |

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

| W/B NO. | PIN NO. | W/B NO. | PIN NO. | W/B NO. | PIN NO. |
|---------|---------|---------|---------|---------|---------|
| 1 | C2 | 21 | H6 | 41 | A7 |
| 2 | C3 | 22 | H8 | 42 | B6 |
| 3 | D3 | 23 | G8 | 43 | B3 |
| 4 | C1 | 24 | G7 | 44 | A2 |
| 5 | D2 | 25 | F7 | 45 | A3 |
| 6 | D1 | 26 | F6 | 46 | A1 |
| 7 | E1 | 27 | E6 | 47 | B1 |
| 8 | E2 | 28 | F8 | 48 | B2 |
| 9 | F1 | 29 | E7 | | |
| 10 | E3 | 30 | E8 | | |
| 11 | F3 | 31 | D8 | | |
| 12 | F2 | 32 | D7 | | |
| 13 | G2 | 33 | C8 | | |
| 14 | G1 | 34 | D6 | | |
| 15 | H1 | 35 | C6 | | |
| 16 | H3 | 36 | C7 | | |
| 17 | H2 | 37 | B7 | | |
| 18 | G3 | 38 | B8 | | |
| 19 | G6 | 39 | A8 | | |
| 20 | H7 | 40 | A6 | | |

| | |
|-----|----|
| S/R | NC |
| D/A | NC |

